

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-4. (Canceled)

5. (Currently Amended) A system comprising:

a chamber to apply a plating solution to plate one or more wafers;

a plurality of tanks to separately hold a metal and one or more of a complexing agent, a buffer, a pH adjuster and a reducing agent; and

a piping system having a plurality of segments, including a plurality of in-line heaters for a subset of the segments, to ~~separate~~ separately route, in-line heat, and after heating, mix to form the plating solution, substantially just prior to application, the metal and the one or more of a complexing agent, a buffer, a pH adjuster and a reducing agent, ~~in-line heat the metal and the one or more of a complexing agent, a buffer, a pH adjuster and a reducing agent.~~

6. (Original) The system of claim 5, wherein the plurality of tanks comprise a tank to store a selected one of Co, Cu, Ni, Fe, Ag, Au, Pt, Pd and Ru.

7. (Currently Amended) The system of claim 5, wherein the plurality of tanks comprise a tank to store ~~either one of~~ a selected one of a citric acid and EDTA to be used as a complex agent, a selected one of NH₄Cl and a boric acid to be used as a buffer, a selected one of KOH and TMAH to be used at a pH adjuster, or a selected one of DMAB, hypophosphite, formaldehyde, and glyoxylic acid to be used as a reducing agent.

8. (Currently Amended) The system of claim 5, wherein the in-line heaters are capable of in-line heating the metal and the one or more of a complexing agent, a buffer, a pH adjuster and a reducing agent to an application temperature in a range of ~~30 C - 90 C~~ 30°C - 90°C.

9-40. (Canceled)

41. (New) The system of claim 5, wherein the plurality of tanks are configured to separately hold the metal and the one or more of a complexing agent, a buffer, a pH adjuster and a reducing agent at room temperature.